



Final Product Change Notification

202606006F01 : PTN3460 Family HVQFN56 Wire Conversion from Gold to Copper

Note: This notice is NXP Company
Proprietary.

Issue Date: Jun 19, 2026 Effective Date: Nov 02, 2026

Dear Emma Tempest,

Here is your personalized communication about an NXP notification.
For detailed information we invite you to [view this notification online](#)

Management summary

NXP will change the wire for the bonding of the PTN3460 Family products, from gold to copper for improved manufacturing logistics. This will align the manufacturing process and flow of this product to industry/factory standard.

Change Category

- | | | | | |
|--|---|--|--|---|
| ☐ Wafer
Fab
Process | ☐ Assembly
Process | ☐ Product Marking | ☐ Test
Process | ☐ Design |
| ☐ Wafer
Fab
Materials | ☒ Assembly
Materials | ☐ Mechanical Specification | ☐ Test
Equipment | ☐ Errata |
| ☐ Wafer
Fab
Location | ☐ Assembly
Location | ☐ Packing/Shipping/Labeling | ☐ Test
Location | ☐ Electrical
spec./Test
coverage |
| ☐ Firmware ☐ Other | | | | |

Notification Overview

Description

ATKH will convert to Copper wire BOM (Bill of materials) for this product.

BOM information for HVQFN56 package

- Wire type from Au 20um to Cu 20um
- Die attach from QMI-519 to ADH, EN-4900
- Mold compound from CEL-9220 to CEL-9240
- Leadframe material from CuFe2P(NiPdAu) to CuFe2P(RT-NiPdAu)

Reason

Copper wire will reduce logistics risks in production, by moving the product(s) to latest factory standards.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jan 20, 2027

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jul 19, 2026.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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